

XXBX Power Shim – XBP

XBP User Guide v1.0

Jens-Peter Kaps
jkaps@gmu.edu

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George Mason University
Fairfax, Virginia



cryptography.gmu.edu



www.gmu.edu

Cryptographic Engineering Research Group

Department of Electrical and Computer Engineering George Mason University
3100 Engineering Building, 4400 University Drive, Fairfax, VA 22030-4444, USA
Voice: (703) 993-1561, Fax: (703) 993-1601

Chapter 1: Introduction

The XXBX Power Shim (XBP) connects the Harness (XBH) to the Device under test (XBD). Figure 1.1 shows a typical XXBX setup with the XBP placed between the XBH and the XBD. All signals from the XBH to the XBD pass through the XBP. The main purpose of the XBP is to sense the current drawn by the XBD, amplify its value and pass it on to the XBH for measurement.

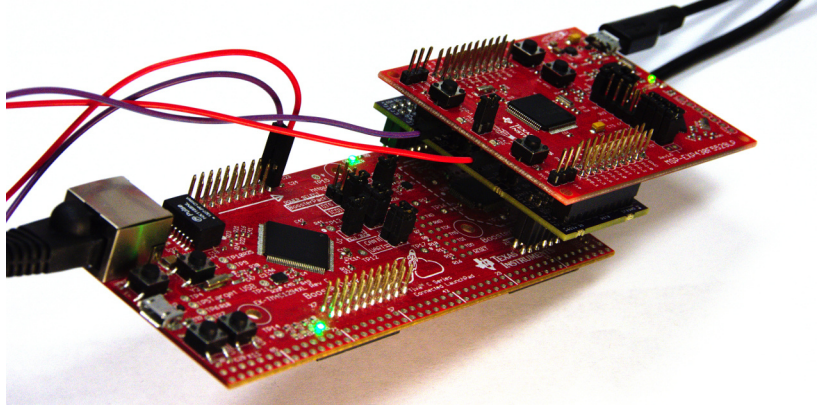


Figure 1.1: XXBX Setup with XBH on the bottom followed by XBP in the middle and XBD on top

1.1 XBP Current Sensing and Amplification

The power consumed by a device can be computed from the current I that it draws and its supply voltage V_{CCD} as $P = I \cdot V_{CCD}$. The energy it consumes for executing a particular task is the integral of P over the run time. As the voltage V_{CCD} is fixed for a particular XBD we only have to measure the current.

The current measured by sensing the voltage drop across a small shunt resistor R_S . The shunt resistor could be placed between the voltage source and the device or between the device and ground called high-side and low-side current sensing respectively. We opted for high-side current sensing (see Fig 1.2) as it eliminates the problems associated with multiple ground paths. The drawback of high-side sensing is the higher common-mode voltage which is the average voltage before and after the shunt.

The shunt resistor should be very small as to not have a large influence on the supply voltage to the XBD. As the voltage drop across a small resistor will also be very small, it has to be amplified. Furthermore, the low input resistance of analog to digital converters (ADCs) makes a direct measurement unfeasible. Hence, we use a current-shunt monitor (CSM), i.e. the INA225 from Texas Instruments. It has a programmable gain setting between 25 and 200, a buffered output

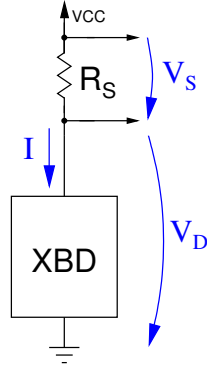


Figure 1.2: High-Side Current Sensing

so that it can drive an ADC input, and a 125 kHz bandwidth, and supports high common-mode voltages.

$$I_{res} = \frac{V_{CSM}}{2^{ADCbits}} \quad (1.1)$$

The current measurement resolution is shown in (1.1). The maximum input voltage to the ADC is 3.3V. Therefore

$$V_{CSM} = 3.3 \text{ V} = V_S \cdot \delta_{CSM} = R_S \cdot I \cdot \delta_{CSM}$$

where δ_{CSM} is the gain of the CSM. When using a 1Ω R_S we achieve a current resolution of $16.5 \mu\text{A}$ at 200 gain, topping out at 32 mA, and $132 \mu\text{A}$ resolution at a gain of 25 topping out at 132 mA.

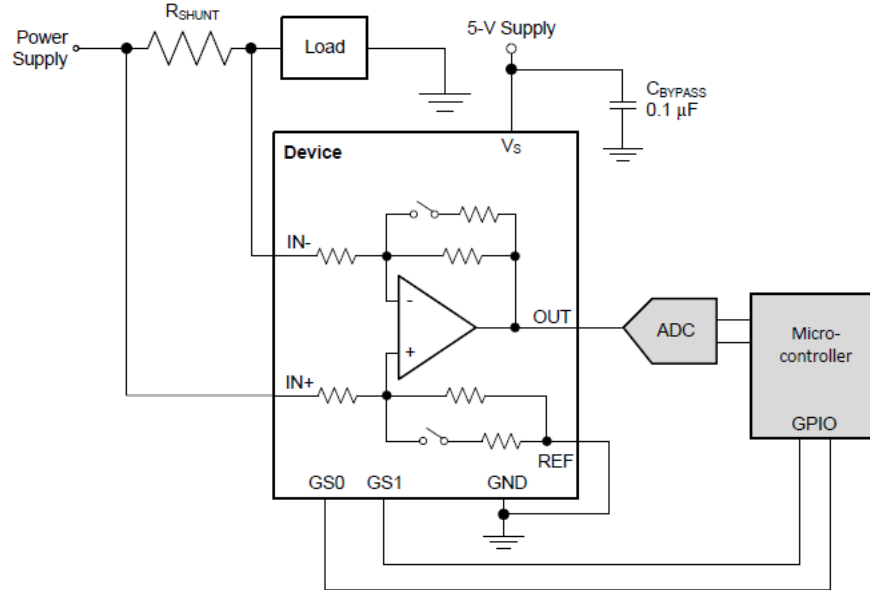


Figure 1.3: Block Diagram of the INA225 CSM

1.2 Optional Functionality

Because of its location in an XXBX setup, we were able to integrate additional functionality which leads to a cleaner setup.

1.2.1 I²C Pull-Up Resistors

The I²C bus requires pull-up resistors. The XBH does not have pull-up resistors on its I²C pins. Only some XBDs either have these pull-up resistors or can be configured to use internal pull-up resistors. We therefore decided to provide a place for pull-up resistors on the XBP. They can be put on the board depending on the users needs.

1.2.2 Power Regulation

The operating voltage for an XBD (V_{CCD}) has to pass through the XBP to measure the current consumption. As V_{CCD} depends on the particular XBD, it makes sense to provide a place on the XBP for a voltage regulator. This enables the user to supply all XBP's with 5 V and have the voltage regulator on the XBP produce the voltage required for each individual XBD.

Chapter 2: XBP Configuration

2.1 Shunt Resistor Selection

R_S

2.2 Supply Voltages

The XBP uses three voltage supplies. The first supply, called V_{CCH} uses 3.3 V from the XBH and powers the I²C pull-up resistors, the activity LED, and the level shifters. The second supply, called V_{CCP} uses 5 V and powers the current sense amplifier of the XBP and the power LED. The third supply is V_{CCD} which powers the XBD.

2.2.1 Powering the XBP

In this section we only discuss how to supply V_{CCH} and V_{CCP} . There are two options to power the XBP. Option one is to power the XBP from the XBH using the LaunchPad connector. This only works if the XBP is directly plugged into the LaunchPad connector on the XBH, we call this an XBP0. Then the XBH can supply V_{CCH} and V_{CCP} . Please close solder jumper **SJ4** and solder jumper **SJ5** and do not connect the power connector's V_{CCH} and V_{CCP} pins to the XBH. They can be used to power another XBP though.

The other option is to power the XBP through the power connector on the front (see Fig. 2.1). This works for XBP0 through XBP3. Please make sure that the solder jumper **SJ4** and solder jumper **SJ5** are **open**. V_{CCH} of 5 V and V_{CCP} of 3.3 V can be wired to the corresponding pins on the XBH or the power connector of the XBP0 if the XBP0 is supplied directly from the XBH through the LaunchPad connectors.

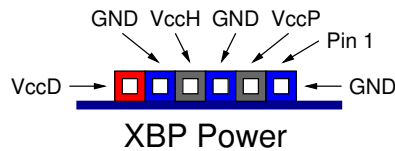


Figure 2.1: XBP Power Connector as Viewed from Front of PCB

2.2.2 Powering the XBD

Power for the XBD can be provided through the power connector's V_{CCD} pin. Optionally V_{CCD} can be generated on the XBP from the 5 V V_{CCP} . If this is desired, please populate **IC1** with an LDO voltage regulator in a SOT-89-3 package. An example is the Microchip MCP1702T-3302E/MB 3.3 V regulator.

Using XBDs with $V_{CC} = 3.3\text{ V}$

If your XBD uses a $V_{CC} = 3.3\text{ V}$ and has a LaunchPad connector, you can plug it directly on top of the XBP. Otherwise you can use the XBD connector on the back of the XBP (see Fig. 2.2) and close solder jumpers **SJ1**, **SJ2**, and **SJ3** as you don't need voltage level shifting. In either case, please check Section 3 in this guide for details on particular XBDs.

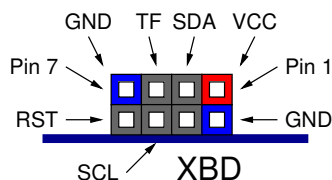


Figure 2.2: XBD Connector as Viewed from Back of PCB

Using XBDs with $V_{CC} \neq 3.3\text{ V}$

Such XBDs can only be connected through the XBD connector on the back (Fig 2.2). The FETs Q3 through Q8 and the resistors R9 through R11 have to be populated. Please make sure that solder jumpers **SJ1**, **SJ2**, and **SJ3** are open. V_{CCD} can be higher or lower than 3.3 V .

2.3 I²C Pull-Up Resistors

The XBP can provide the pull-up resistors for I²C. These are needed only once on an I²C bus. We suggest that you populate **R3** and **R4** using 10kOhm resistors (size: 0604) on the first XBP (XBP0).

2.4 Usage without XBH

The XBP can be used also without an XBH as an experimenter's board for the INA225 current-shunt monitor. The XBH requires V_{CCP} of 5 V to be supplied through its power connector (see Fig. 2.1). The power for the device under test can be supplied as described in section 2.2.2. The amplified voltage drop over the shunt can be measured by through the SMA connector **X1**. The gain of the amplifier can be set through jumper JP5. The jumper settings required for the different gains are printed on the circuit board. The device under test will get its power from the XBD connector (see Fig. 2.2). Only pins 1 and 2, V_{CC} and GND respectively, have to be used.

Chapter 3: XBX Devices under Test (XBD)

3.1 TI Stellaris® LM4F120 LaunchPad

Neither the Debug, nor the Device USB should be connected for power measurements. The $+3.3V$ line on pin J1.1 of the boosterpack connector is connected directly to the In-Circuit Debugger. Therefore, it is recommended to select on the XBP to power the XBD via the external XBD connector and not via the boosterpack connector. On the TI Stellaris Launchpad, the VDD jumper has to be pulled and the external 3.3V has to be supplied to the right pin. The green power LED on the Launchpad lights up when the 3.3V are supplied to the left (wrong) pin. The *PWR Select* switch can be in any position and won't affect the measurements.

3.2 TI Tiva™ C Series TM4C123G LaunchPad

The circuit connections are the same as on the TI Stellaris LaunchPad. Please follow those instructions. Supply voltage is 3.3V with a maximum current of 300 mA.

3.3 TI MSP430F5529 LaunchPad™

For precise current measurements remove all jumpers from the isolation jumper block with the exception of the ground (GND) jumper.

3.4 TI MSP430FR6989 LaunchPad™

For precise current measurements remove all jumpers from the isolation jumper block with the exception of the ground (GND) jumper. Supply voltage is 3.3V with a maximum current of 2.7 mA not including LEDs or external circuitry.

Chapter 4: XBP Assembly

4.1 XBP Connections

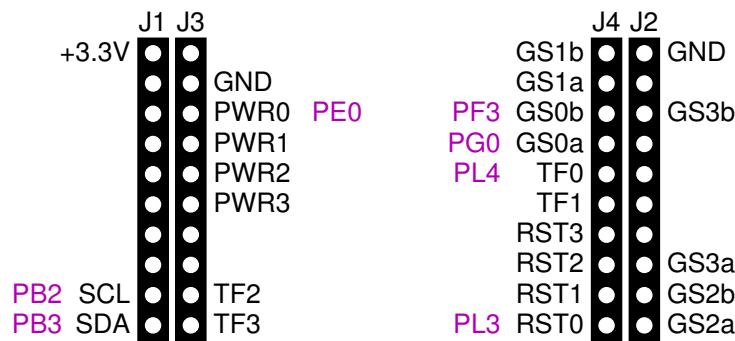


Figure 4.1: Boosterpack Connector XBH as Viewed from Top of PCB

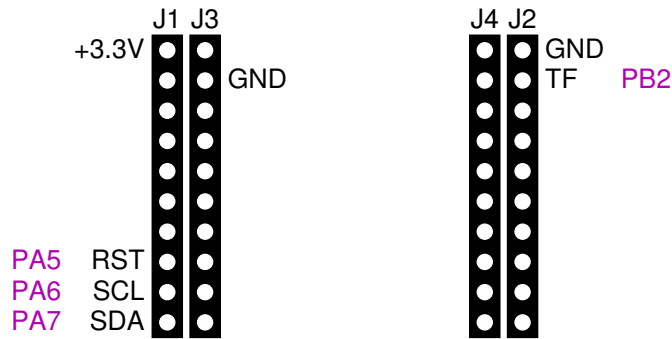


Figure 4.2: Boosterpack Connector XBD as Viewed from Top of PCB

Table 4.1: Pin Configuration of Boosterpack Connector for XBH

| Connector | Pin | Net | Comment |
|-----------|-------|-----------|--|
| J1 | 1 | +3V3 | Supply Voltage V_{CCH} from XBH for I ² C pull-up resistors on XBP0 |
| J1 | 9 | SCL | I ² C Serial Clock |
| J1 | 10 | SDA | I ² C Serial Data |
| J3 | 21 | +5V | Supply Voltage V_{CCP} from XBH for the XBP0 |
| J3 | 23 | PWR0 | Analog signal of current consumption of XBD0 from XBP0 |
| J4 | 37/38 | GS0a/GS0b | Gain select for current monitor of XBD0 on XBP0 |
| J4 | 36 | TF0 | Timer Flag from XBD0 |
| J4 | 31 | RST0 | Reset of XBD0 |
| J3 | 24 | PWR1 | Analog signal of current consumption of XBD1 from XBP1 |
| J4 | 39/40 | GS1a/GS1b | Gain select for current monitor of XBD1 on XBP1 |
| J4 | 35 | TF1 | Timer Flag from XBD1 |
| J4 | 32 | RST1 | Reset of XBD1 |
| J3 | 25 | PWR2 | Analog signal of current consumption of XBD2 from XBP2 |
| J2 | 11/12 | GS2a/GS2b | Gain select for current monitor of XBD2 on XBP2 |
| J3 | 29 | TF2 | Timer Flag from XBD2 |
| J4 | 33 | RST2 | Reset of XBD2 |
| J3 | 26 | PWR3 | Analog signal of current consumption of XBD3 from XBP3 |
| J2 | 13/18 | GS3a/GS3b | Gain select for current monitor of XBD3 on XBP3 |
| J3 | 30 | TF3 | Timer Flag from XBD3 |
| J4 | 34 | RST3 | Reset of XBD3 |
| J2 | 20 | GND | |
| J3 | 22 | GND | |

Table 4.2: Pin Configuration of Boosterpack Connector for XBD

| Connector | Pin | Net | Comment |
|-----------|-----|------|---|
| J1 | 1 | +3V3 | Supply Voltage, current is measured by XBP |
| J1 | 9 | SCL | I ² C Serial Clock |
| J1 | 10 | SDA | I ² C Serial Data |
| J2 | 16 | RST | Reset of XBD |
| J2 | 19 | TF | Timer Flag to start/stop execution timer on XBH |
| J2 | 20 | GND | |
| J3 | 22 | GND | |